- **Three Bidirectional Transceivers**
- Driver/Receiver Meets or Exceeds the Requirements of ANSI Standard RS-485 and ANSI Standard X3.131-1986 (SCSI)
- **High-Speed Advanced Low-Power Schottky** Circuitry
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- Wide Positive and Negative Input/Output Bus Voltages Ranges . . . - 7 V to 12 V
- Driver Output Capacity . . . ±60 mA
- **Driver Positive and Negative Current** Limiting
- **Thermal Shutdown Protection**
- Receiver Input Sensitivity . . . ±200 mV Max
- Receiver Input Impedance . . . 12 k Ω Min
- Receiver Input Hysteresis . . . 50 mV Typ
- **Operates From a Single 5-V Supply**
- **Low Supply-Current Requirements** 72 mA Max
- Glitch-Free Power-up and Power-Down **Protection**

description

The SN75ALS1711 triple differential bus

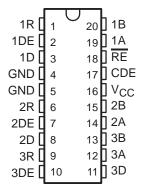
transceiver is a monolithic integrated circuit designed for bidirectional data communication on multipoint bus transmission lines. It is designed for balanced

transmission lines and meets ANSI Standard RS-485 and ANSI Standard X3.131-1986 (SCSI).

The SN75ALS1711 operates from a single 5-V power supply. The drivers and receivers have individual active-high and active-low enables, respectively, which can be externally connected together to function as a direction control. The driver differential output and the receiver differential input pairs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or V_{CC} is at 0. These ports feature wide positive and negative common-mode voltage ranges making the device suitable for party-line applications.

The SN75ALS1711 is characterized for operation from 0°C to 70°C.

DW OR N PACKAGE (TOP VIEW)



Function Tables

EACH DRIVER

INPUT	ENA	ABLES	OUT	PUTS
D	DE	CDE	Α	В
Н	Н	Н	Н	L
L	Н	Н	L	Н
X	L	Χ	Z	Z
X	Х	L	Z	Z

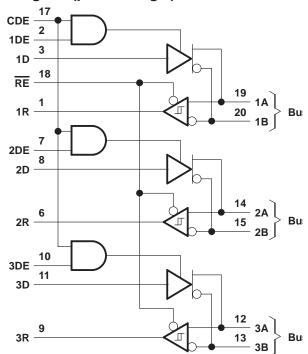
EACH RECEIVER

DIFFERENTIAL INPUTS A – B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
$V_{ID} = -0.2 \text{ V to } 0.2 \text{ V}$	L	?
V _{ID} ≤ −0.2 V	L	L
X	Н	Z
Open	L	Н

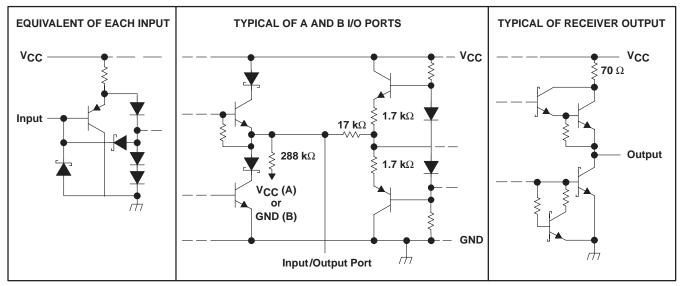
H = high level, L = low-level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

logic symbol[†] 17 CDE -G5 1DE 5EN1 2DE 5EN2 10 5EN3 3DE 18 RE EN4 1 ▽ 1D -20 1 ▽ 1 **▽4** П 2 ▽ 2 ▽ 1 2R П 3 ▽ \triangleright 3D 3 ▽ 1 **∀**4 П

logic diagram (positive logic)



schematics of inputs and outputs



All values are nominal.



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SLLS117B - APRIL 1991 - REVISED MAY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.5 V to 7 V
Enable input voltage range, V _I	\dots -0.5 V to V _{CC} + 0.5 V
Input voltage range, V _I : Driver	\dots -0.5 V to V _{CC} + 0.5 V
Receiver	–9 V to 14 V
Output voltage range, VO: Driver	–9 V to 14 V
Receiver	-0.5 V to V_{CC} + 0.5 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stq}	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
DW	1125 mW	9.0 mW/°C	720 mW
N	1150 mW	9.2 mW/°C	736 mW

recommended operating conditions

		MIN	TYP	MAX	UNIT
Supply voltage, V _{CC}				5.25	V
Common-mode input voltage at any bus terminal, V _{IC} (see Note 2)				12	V
High-level input voltage, VIH	D, DE, RE, CDE	2			V
Low-level input voltage, V _{IL}	D, DE, RE, CDE			0.8	V
High lovel output ourrent leve	Driver			-60	mA
High-level output current, IOH	Receiver			-400	μΑ
Low-level output current, IOL	Driver			60	mA
Receiver				8	ША
Operating free-air temperature, T _A				70	°C

[‡] The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 2: Differential-input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
٧ıK	Input clamp voltage	I _I = –18 mA				-1.5	V
VO	Output voltage	IO = 0		0		6	V
V _{OD1}	Differential output voltage	I _O = 0		1.5		5	V
V _{OD2}	Differential output voltage	$R_L = 54 \Omega$,	See Figure 1	1.5		5	V
V _{OD3}	Differential output voltage	See Note 3 and F	igure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage [‡]	R _L = 54 Ω,	See Figure 1			±0.2	V
Voc	Common-mode output voltage	R _L = 54 Ω,	See Figure 1			3 -1	V
Δ V _{OC}	Change in magnitude of common-mode output voltage‡	R _L = 54 Ω,	See Figure 1			±0.2	V
lo-	High-impedance state output current	Output disabled, V _{CC} = 5.25 V	V _O = 12 V			1	mA
loz			V _O = 7 V			-0.8	IIIA
lН	High-level input current, DE, EN, CDE	V _{IH} = 2.4 V				20	μΑ
I _{IL}	Low-level input current, DE, EN, CDE	V _{IL} = 0.4 V				-200	μΑ
laa	Short circuit output current	V _O = 12 V				-250	mA
los	Short-circuit output current	V _O = 7 V				250	IIIA
loo	Outrack course of	No load	Outputs enabled		48	72	mA
Icc	Supply current		Outputs disabled		30	48	IIIA

NOTE 3: This applies for both power on and off; refer to ANSI Standard RS-485 for exact conditions.

switching characteristics, V_{CC} = 5 V \pm 5%, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
tPLH	Differential propagation delay time, low- to high-level output	$R_L = 54 \Omega$,	C _L = 100 pF,	8	13	22	
tPHL	Differential propagation delay time, high- to low-level output			8	15	22	ns
^t PZH	Output enable time to high level		S1 open,	30	50	60	
t _{PHZ}	Output disable time from high level	$R_L = 110 \Omega$, S2 close		4	16	30	
tPZL	Output enable time to low level	See Figure 4	S1 closed,	16	26	45	ns
tPLZ	Output disable time from low level]	S2 open	4	8	20	



[†] All typical values are at $V_{CC} = 5$ V and $T_A = 25$ °C. ‡ $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST C	TEST CONDITIONS		TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$			0.2	V
VIT-	Negative-going input threshold voltage	$V_0 = 0.5 V$,	$I_O = 4 \text{ mA}$	-0.2‡			V
V _{hys}	Hysteresis voltage (V _{IT+} - V _{IT-})				50		mV
VIK	Input clamp voltage, RE	I _I = 18 mA				-1.5	V
Vон	High-level output voltage	$I_{OH} = -0.4 \text{ mA}$		2.4			V
VOL	Low-level output voltage	I _{OL} = 4 mA				0.5	V
loz	High-impedance-state output current	$V_{CC} = 5.25 \text{ V},$	V _O = 0.4 V to 2.4 V			±20	μΑ
	Line input current	Other input at 0, See Note 3	V _I = 12 V			1	mA
'			V _I = 7 V			-0.8	
lн	High-level input current, RE	V _{IH} = 2.4 V				20	μΑ
I _{IL}	Low-level input current, RE	V _{IL} = 0.4 V				-200	μΑ
rį	Input resistance			12			kΩ
los	Short-circuit output current§	V _O = 0		-15		-130	mA
Lan	Supply current	No load	Outputs enabled		48	72	mΛ
ICC			Outputs disabled		30	48	mA

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V and T_A = 25°C.

NOTE 3: This applies for both power on and off; refer to ANSI Standard RS-485 for exact conditions.

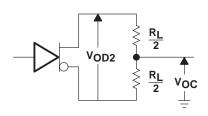
switching characteristics, V_{CC} = 5 V \pm 5%, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	See Figures 5 and 6		13	20	37	nc
tPHL	Propagation delay time, high- to low-level output			13	20	37	ns
^t PZH	Output enable time to high level		S1 to 1.5 V, S2 open, S3 closed	3	9	20	
tPHZ	Output disable time from high level	Coo Figures F and 7		8	15	22	20
tPZL	Output enable time to low level	See Figures 5 and 7	S1 to -1.5 V, S2 closed,	5	10	20	ns
^t PZL	Output enable time to low level		S3 open	5	9	16	

[‡] The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

[§] Not more than one output should be shorted at one time.

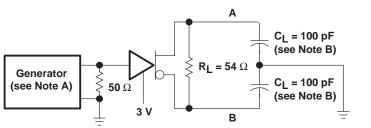
PARAMETER MEASUREMENT INFORMATION



 $\begin{array}{c|c}
375 \Omega \\
\hline
V_{\text{OD3}} & 60 \Omega \\
\hline
V_{\text{test}} \\
\hline
375 \Omega
\end{array}$

Figure 1. Driver $V_{\mbox{\scriptsize OD}}$ and $V_{\mbox{\scriptsize OC}}$

Figure 2. Driver V_{OD3}



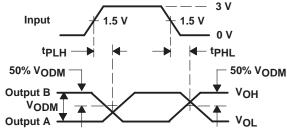
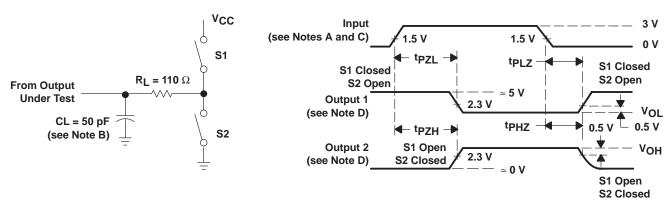


Figure 3. Driver Propagation Delay Times



NOTES: A. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_{O} = 50 \Omega$, $t_{r} \leq$ 10 ns, $t_{f} \leq$ 10 ns.

- B. C_I includes probe and jig capacitance.
- C. Each enable is tested separately.
- D. Output 1 and output 2 are outputs with internal conditions such that the output is low or high except when disabled by the output control.

Figure 4. Driver Enable/Disable Times



PARAMETER MEASUREMENT INFORMATION

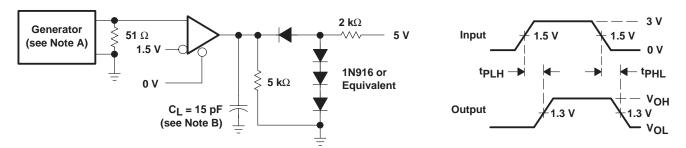
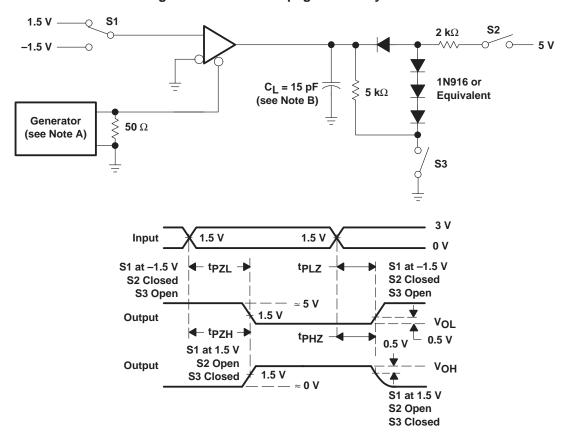


Figure 5. Receiver Propagation Delay Times



NOTES: A. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , $t_f \leq$ 10 ns, $t_f \leq$ 10 ns. B. C_L includes probe and jig capacitance.

Figure 6. Receiver Enable/Disable Times



PACKAGE OPTION ADDENDUM

6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS1711N	OBSOLETE	PDIP	N	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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